



The **25<sup>th</sup> Asian Session of Advanced Metallization Conference (ADMETA)** will be held at the Global Convention Plaza, **Seoul National University, Seoul, Korea** during **September 16–18, 2015**.

ADMETA is devoted to leading-edge research in the field of advanced interconnect and electronic packaging in materials, processing, design, simulation, and reliability. This premier conference will also provide an excellent opportunity for researchers, engineers, and students to discuss recent advances and new research directions.

The conference will feature several technical sessions (oral presentations and posters), five tutorial sessions, plenary sessions (keynote speeches), and exhibitions. The tutorials offer introductory overview and state-of-the-art technology reviews in a condensed format. Special posters presented at the ADMETA will be awarded the Best Poster Awards.

The conference seeks papers on all aspects of interconnects for device, circuit board and system-level applications. The deadline for submission of abstracts is June 20, 2015. The organizing committee eagerly awaits your participation in ADMETA plus 2015 and looks forward to welcoming you in Seoul, Korea.

### Topics of Interest

The ADMETA conference will include all fundamental and applied sciences and technologies in the field of traditional interconnects, emerging interconnects, 3D interconnects, and their related materials and processes. Topics may include from, but are not limited to, the following area:

- Advanced Interconnects – Components to Systems
- Materials and unit Processes (Metal, dielectric, barrier, Wet, CMP, PVD, CVD, ALD, ECD, SAM, etc)
- 3D Integration & Packaging
- Interconnect technologies for Display
- Emerging Interconnect Technology – Flexible, Stretchable, Ultra-Thin PCB, etc
- Design for Reliability and Failure Analysis
- Modeling and Simulation of Advanced Metallization and IC thermal Management

### Keynote Speakers

- **Dr. Seok-Hee Lee** (Co-Chair, SK Hynix Inc.)
- **Dr. Satoshi Tanimoto** (Nissan Arc.)

### Tutorial Program

The 2015 ADMETA will feature 5 tutorials covering a variety of topics to complement the technical sessions. The following tutorials will be offered on Wednesday Sep. 16, 2015.

- Electroplating Fundamentals and Applications (**Prof. Oh Joong Kwon**, Incheon National University)
- Atomic Layer Deposition (**Prof. Han-Bo-Ram Lee**, Incheon National University)
- Chemical Mechanical Polishing (**Prof. Jin-Goo Park**, Hanyang University)
- 3D Integration & Packaging (**Prof. Sarah Eunkyung Kim**, Seoul National University of Sci. & Tech.)
- Interconnect Reliability (**Dr. Young-Joon Park**, Texas Instruments Inc.)



## Invited Speakers

- **Dr. Young-Joon Park** (Texas Instruments Inc.) – Intrinsic Reliability of Interconnects and MOSFETs
- **Dr. Tae-Kyu Lee** (Cisco Systems Inc.) – Link Between Degradation Mechanisms and Microstructure Signatures in Solder Joint Interconnects
- **Prof. Xin-Ping Qu** (Fudan University) - Novel Alloy Diffusion Barrier for Advanced Copper Interconnect
- **Prof. Chee Lip Gan** (Nanyang Technological University) - Copper Nanoparticles Enabled Low Temperature Bonded Interconnections
- **Dr. Manabu Tsujimura** (CTO, Ebara Corporation) - The Way to Zero's –The future of Semiconductor Device and CMP Technologies
- **Dr. Sintaro Sato** (Fujitsu Laboratories Ltd.) - Nanocarbon Interconnects with Resistivity and Reliability Better than Cu
- **Prof. Hyungjun Kim** (Yonsei University) – Atomic Layer Deposition of Transition Metals for Interconnect Technology

## Important Dates

- **Abstract submission by: July 18, 2015**
- **Authors submit abstracts to: E-mail: [admata2015@gmail.com](mailto:admata2015@gmail.com)**
- Pre-registration by: August 20, 2015
- SCI journal submission by: Immediately after the conference (Selected papers will be published in JJAP special issue)

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